

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6129xxxx7R-G
Typical Mass: 1 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.064	Silicon	64100	7440-21-3
		- Arsenic	<1	7440-38-2
Lead pad	0.239	Nickel	239300	7440-02-0
		Gold	1500	7440-57-5
Die attach	0.008	Epoxy Resin	8100	—
		Acrylic Resin	4900	—
Bonding wire	0.030	Gold	30200	7440-57-5
Resin	0.570	Silica	570300	60676-86-0
		Epoxy Resin	32600	—
		Phenol Resin	29300	—
		Metal hydroxide	19600	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."